

Fig1 Transmission electron microscopy profiles (TEM) with different etching depths

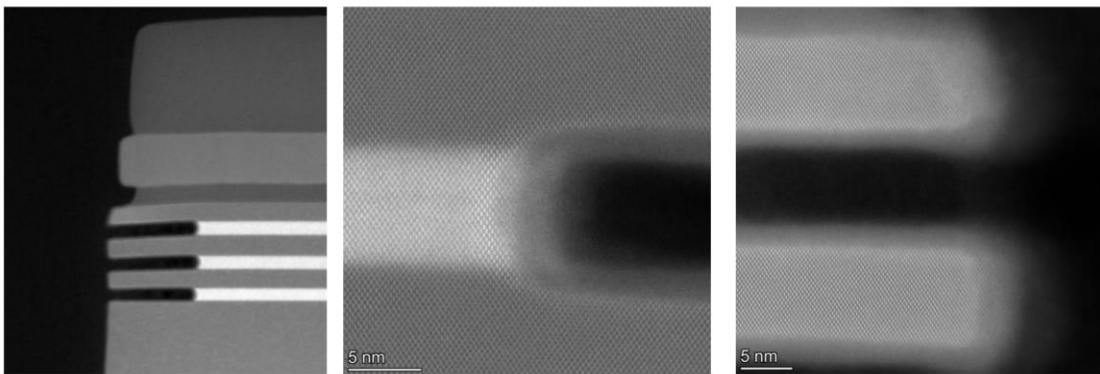


Fig2 High resolution TEM of RPS (Remote Plasma) selective etching SiGe

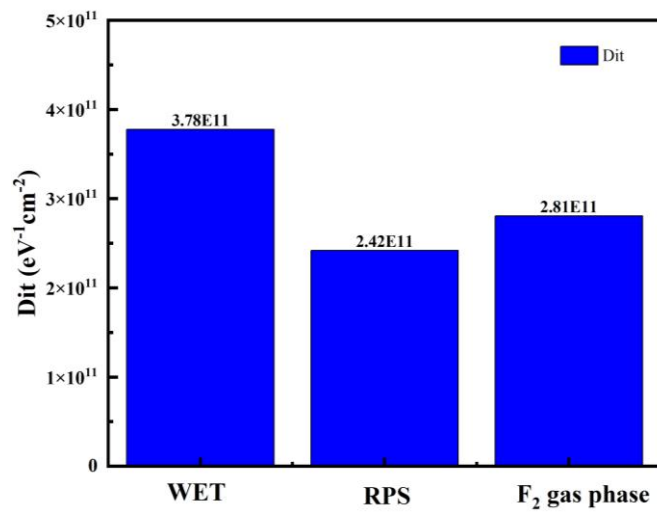


Fig3 Comparison of interface trap density (D_{it}) after selective etching of different SiGe methods

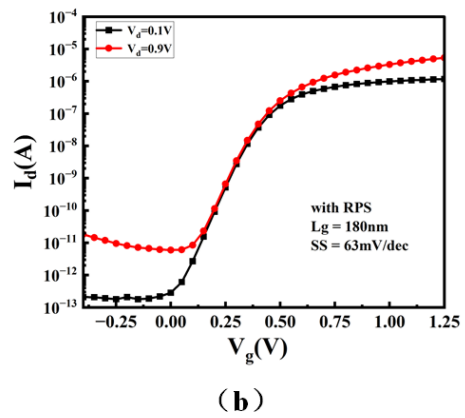
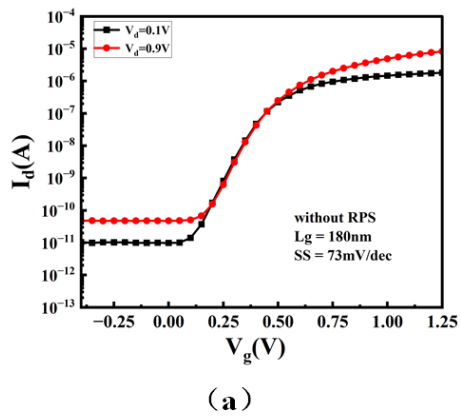
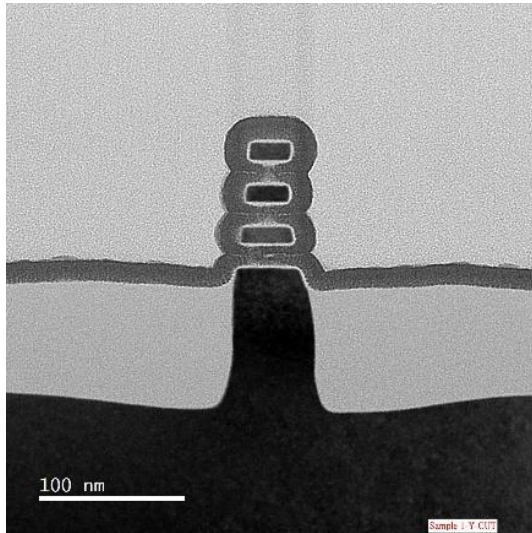


Fig4 Gate all around devices and electrical curves prepared using RPS channel release